

Electrically Conductive Adhesives

Product Name	Description	Key Attributes	Volume Resistivity ($\Omega \cdot \text{cm}$)	Glass Transition Temperature, T_g ($^{\circ}\text{C}$)	Coefficient of Thermal Expansion, CTE (ppm/ $^{\circ}\text{C}$)		Modulus at 25 $^{\circ}\text{C}$ (MPa)	Recommended Cure
					Below T_g	Above T_g		
Acrylate								
LOCTITE ABLESTIK CA 3556HF	Acrylate electrically conductive adhesive	<ul style="list-style-type: none"> • One component • Fast, low-temperature cure • Excellent flexibility • Good adhesion • Low contact resistance 	2.5×10^{-3}	-30	95	278	650	2 min. at 110 $^{\circ}\text{C}$
Epoxy								
LOCTITE ABLESTIK CE 3103WLV	Epoxy electrically conductive adhesive	<ul style="list-style-type: none"> • Pb-free alternative to solder • Low-temperature cure • Stable contact resistance 	8×10^{-4}	114	45	225	4,500	10 min. at 120 $^{\circ}\text{C}$
Silicone								
LOCTITE ABLESTIK ICP 4000	Silicone electrically conductive adhesive	<ul style="list-style-type: none"> • One component • High flexibility • Excellent electrical conductivity • High-temperature performance • Pb-free alternative to solder • High electrical current carrying capability • Low-temperature cure • Outstanding elongation performance • Low outgassing 	6×10^{-5}	-45	N/A	330	101	1 hr. at 130 $^{\circ}\text{C}$